

ABSTRACT

In a method of manufacturing a circuit forming board, a first sheet having a first direction is transferred in a second direction, so that the first direction of the first sheet is parallel to the second direction. Films are
5 stuck onto both surfaces of the first sheet while transferring the first sheet in a third direction orthogonal to the first direction of the first sheet. This method allows a connecting member, such as conductive paste, to electrically couple between layers of the circuit forming board.